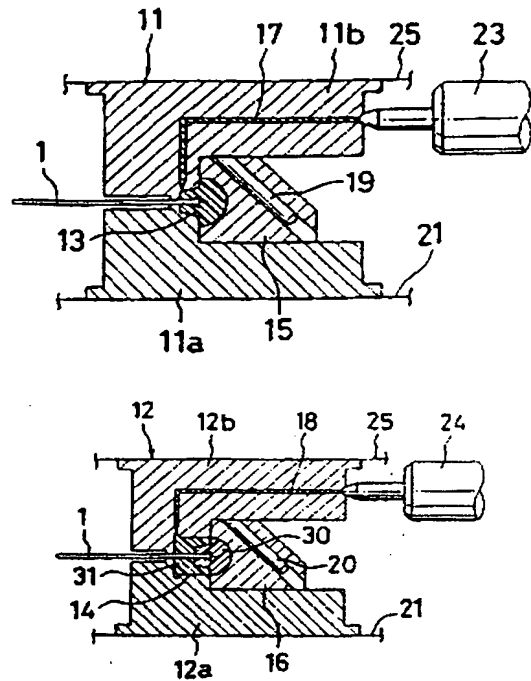


Patent Abstracts of Japan

TITLE : METHOD OF SEALING
LIGHT-EMITTING DIODE WITH RESIN



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